

CLAIMS

We claim:

1. An arrangement comprising:
 - an optoelectronic component with terminal contacts,
 - an electrical component with first electrical contacts and second electrical contacts,
 - a printed circuit board, to which the second electrical contacts of the electrical component are connected, and
 - a flexible conductor arrangement of a planar form and including a plurality of conductor tracks,
 - wherein the plurality of conductor tracks provide an electrical connection between the terminal contacts of the optoelectronic component and the first electrical contacts of the electrical component,
 - wherein the flexible conductor arrangement further comprises a first region with first contact regions and a second region with second contact regions, and
 - wherein at least one of:
 - the optoelectronic component is mounted directly on the first region of the conductor arrangement such that its terminal contacts are connected to the first contact regions of the conductor arrangement, and
 - the electrical component is mounted directly on the second region of the conductor arrangement such that its first electrical contacts are connected to the second contact regions of the conductor arrangement.
2. The arrangement according to Claim 1, wherein the first region of the conductor arrangement is stiffened.
3. Arrangement according to Claim 2, wherein the stiffened region of the conductor arrangement includes a rigid part.

4. The arrangement according to Claim 1, wherein the optoelectronic component is arranged in a package that is supported on the conductor arrangement.

5. The arrangement according to Claim 1, wherein the second region of the conductor arrangement is stiffened.

6. The arrangement according to Claim 5, wherein the stiffened region of the conductor arrangement includes a rigid part.

7. The arrangement according to Claim 6, wherein the second electrical contacts of the electrical component are electrically connected to the printed circuit board by electrical contacts mounted on the rigid part.

8. The arrangement according to Claim 6, wherein the electrical component is mechanically supported on the printed circuit board by the rigid part.

9. The arrangement according to Claim 1, wherein the conductor arrangement is arranged parallel to the printed circuit board and is supported by the printed circuit board in its second region.

10. The arrangement according to Claim 1, wherein the electrical component is arranged in a package.

11. The arrangement according to Claim 10, wherein the package comprises a casting material formed over the electrical component after an electrical connection of the electrical component to the conductor arrangement.

12. The arrangement according to Claim 1, wherein the first region of the conductor arrangement and the second region of the conductor arrangement are formed at opposite ends of the conductor arrangement.

13. The arrangement according to Claim 12, wherein the flexible conductor arrangement is bent in a third region that extends between the first region and the second region.

14. The arrangement according to Claim 1, wherein the first region of the conductor arrangement is aligned substantially perpendicular to the second region of the conductor arrangement.

15. The arrangement according to Claim 1, wherein the flexible conductor arrangement is formed by a flexible conductor.

16. The arrangement according to Claim 1, wherein the conductor tracks of the conductor arrangement are impedance-matched.

17. The arrangement according to Claim 1, wherein an electrical contact of the electrical component is connected to an assigned second contact region of the conductor arrangement by a bonding wire.

18. The arrangement according to Claim 1, wherein a terminal contact of the optoelectronic component is connected to an assigned first contact region of the conductor arrangement by a bonding wire.

19. The arrangement according to Claim 1, wherein the electrical component comprises an unpackaged chip, which is

mounted directly on the second region of the conductor arrangement.

20. The arrangement according to Claim 19, wherein the electrical component comprises a laser driver chip.

21. The arrangement according to Claim 1, wherein the optoelectronic component comprises an unpackaged chip, which is mounted directly on the first region of the conductor arrangement.

22. The arrangement according to Claim 21, wherein the optoelectronic component comprises a laser chip.

23. An arrangement comprising:

a flexible conductor arrangement including a first region having a plurality of first contact structures, a second contact region having a plurality of second contact structures, and a third region including a plurality of conductor tracks, wherein each conductor track extends between a first contact structure of the first contact structures and a corresponding second contact structure of the second contact structures;

an optoelectronic component mounted on the first region of the flexible conductor arrangement, the optoelectronic component including terminal contacts that are respectively electrically connected to the plurality of first contact structures of the flexible conductor arrangement;

a printed circuit board including a plurality of third contact structures; and

an electrical component mounted on the printed circuit board, the electrical component including first electrical contacts that are respectively electrically connected to

corresponding said second contact structures, and second electrical contacts that are respectively electrically connected to corresponding said third contact structures.

24. An arrangement comprising:

a flexible conductor arrangement including a first region having a plurality of first contact structures, a second contact region having a plurality of second contact structures, and a third region including a plurality of conductor tracks, wherein each conductor track extends between a first contact structure of the first contact structures and a corresponding second contact structure of the second contact structures;

an optoelectronic component including terminal contacts that are respectively electrically connected to the plurality of first contact structures of the flexible conductor arrangement;

a printed circuit board including a plurality of third contact structures; and

an electrical component mounted on the flexible conductor arrangement and the printed circuit board such that the second region of the flexible conductor arrangement is positioned between the electrical component and the printed circuit board, the electrical component including:

first electrical contacts that are respectively electrically connected to corresponding said second contact structures, and

second electrical contacts that are respectively electrically connected to corresponding said third contact structures.